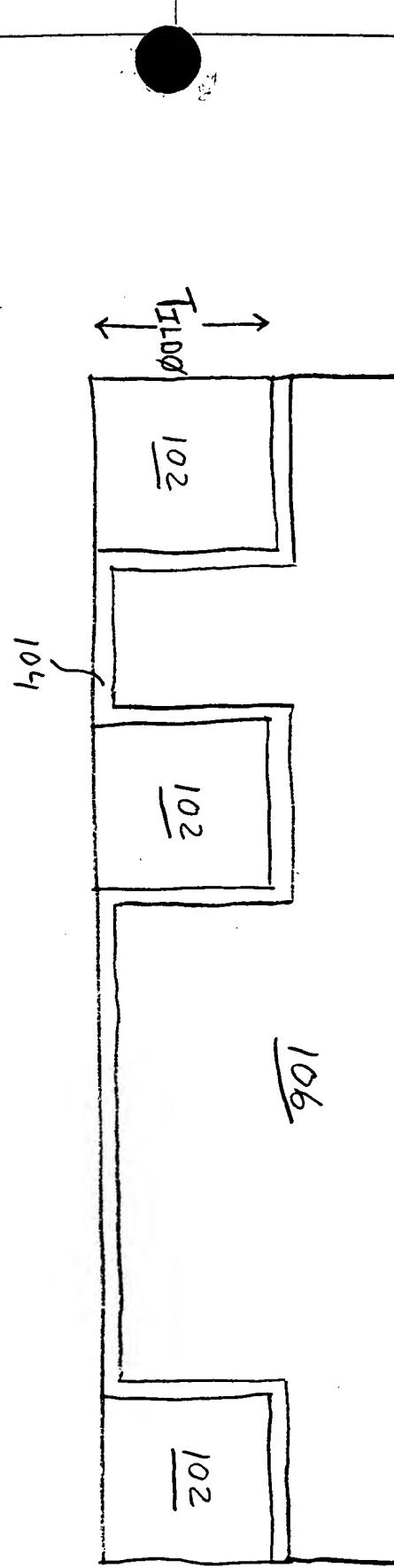


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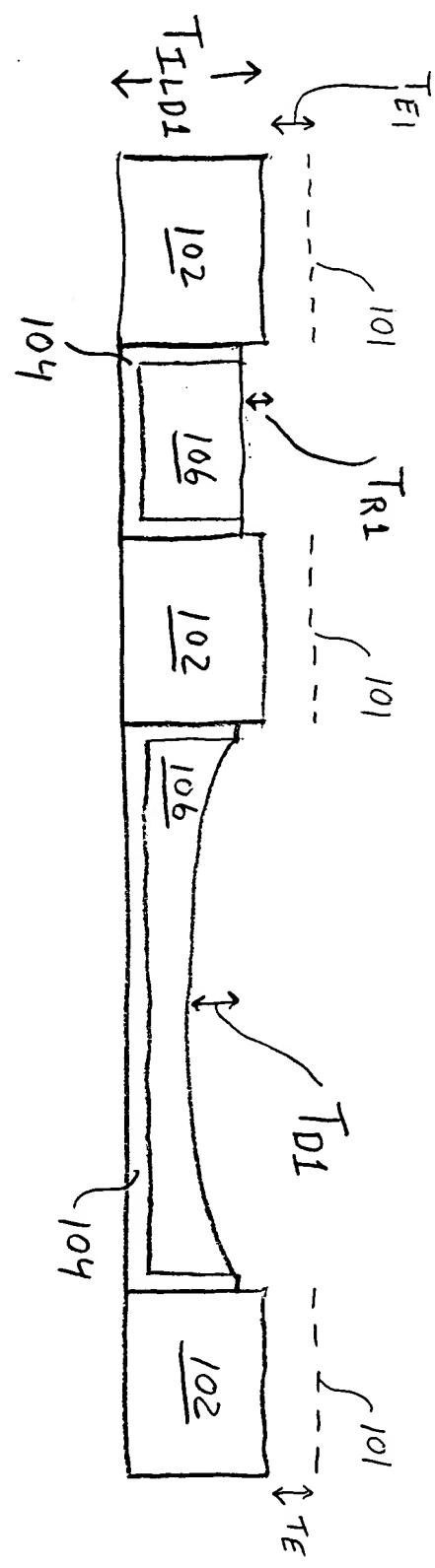


Fig. 2

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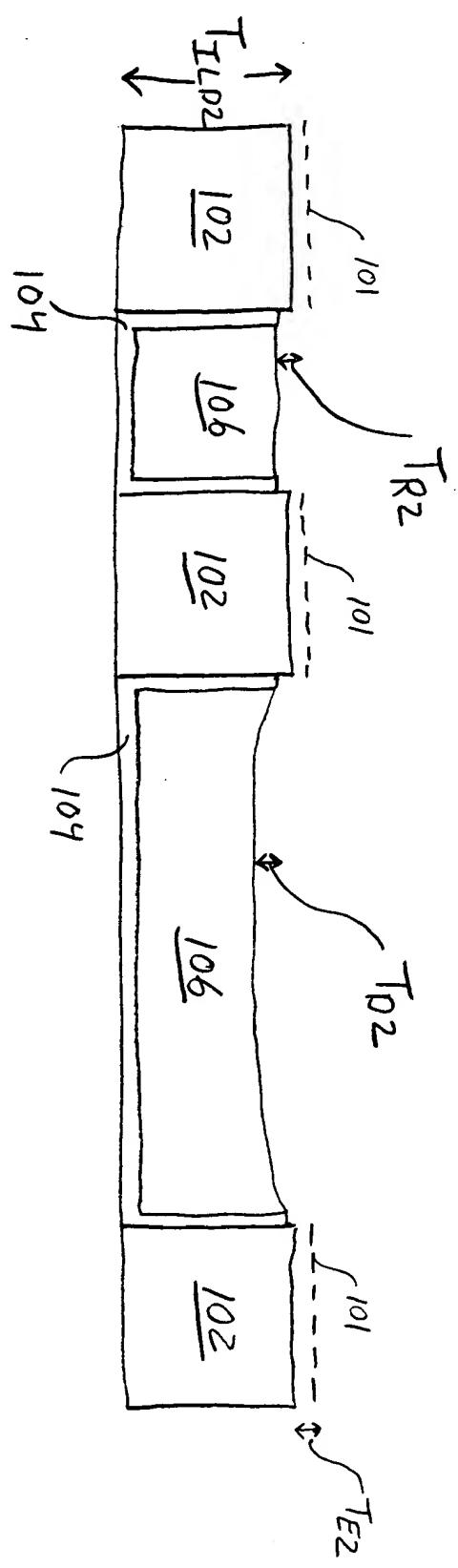


Fig. 3

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402	Provide high pH slurry to polishing pad
404	Bring copper damascene structure thereon into contact with polishing pad
406	Polish copper damascene structure

Fig. 4

Fig. 5

